

## MAGNOVAL® 2067

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Co	m	DC	S	iti	on

MAGNOVAL® 2067 consists of glass cloth, iron powder and a modified epoxy resin.

#### **Application**

MAGNOVAL® 2067 has good magnetic conductivity combined with high resistivity and high mechanical strength. MAGNOVAL® 2067 is used e. g. for slot wedges for induction motors.

#### **Availability**

Thickness: 1 - 10 mm

Thickness tolerance: acc. DIN 40606 (HGW 2372.4)

Dimension:

950 +50/-0 mm x 1020 +20/-0 mm

950 +50/-0 mm x 1400 +20/-0 mm

Slot wedges according drawings.

#### Storability

Unlimited under normal conditions (20° C, 50% r. h.).

#### **Machining Recommendation**

Carbide tipped tools are recommended.

In case of vacuum impregnation we recommend to use POROMAT® 2242 (2248) as bed material for fixing the slot wedges. (see data sheets POROMAT®)

All information given here is based on currently available facts and on the results of experiments performed with all due care in our laboratories. It does not in any way reduce the responsibility of the user for carrying out further tests in order to ensure successful processing and use in specific applications.

ISOVOLTA AG | 2355 Wiener Neudorf Austria

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### TECHNICAL DATA

Properties	Norm	Unit				Value			
Magnetic induction	IPV Nr. 11	Tesla	0.1	0.2	0.3	0.4	0.5	0.6	0.7
Relative permeability [μ(Β)] Tolerance: ± 10 %	IPV Nr. 11	-	2.8	2.9	2.9	2.8	2.6	2.5	2.4
Magnetic field strength	IPV Nr. 11	A/cm	500	1000	1500	2000	2500		
Magnetic induction [B(H)] Tolerance: ± 10 %	IPV Nr. 11	Tesla	0.18	0.35	0.5	0.63	0.73		

Properties	Norm	Unit	Value
Density	ISO 1183	g/cm³	3.5 ± 0.2
Flexural strength at 23°C / 150°C	ISO 178	MPa	≥ 150 / ≥ 120
Modulus of elasticity at 23°C / 150°C	ISO 178	GPa	approx. 12 / approx. 9
Resistivity	IEC 60167	Ohm x cm	$\geq 1 \times 10^6$
Iron content		%	approx. 75
Glass content		%	approx. 7
Resin content		%	approx. 18
Temperature index	IEC 60216	°C	approx. 155

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